

LAYER STACKUP  
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Top  
F.Silkscreen Top silkscreen (White, Direct Printing)  
F.Paste Top paste  
F.Mask Top mask (Green, 0.02mm, Solder Resist, Er=3.8)  
L1 (Sig,PWR) Copper 0.035mm

Dielectric 1 Prepreg  
1/1 FR4 natural 0.0994mm  
3313 RC57% 4.2mil, Er=4.1, LossTg=0.02

L2 (GND) Copper 0.0152mm

Dielectric 2 Core  
1/1 FR4 natural 0.55mm  
0.55mm H/Hwithout copper, Er=4.41, LossTg=0.02

L3 (Sig,PWR) Copper 0.0152mm

Dielectric 3 Prepreg  
1/1 FR4 natural 0.1088mm  
2116 RC54% 4.9mil, Er=4.16, LossTg=0.02

L4 (Sig,PWR) Copper 0.0152mm

Dielectric 4 Core  
1/1 FR4 natural 0.55mm  
0.55mm H/Hwithout copper, Er=4.41, LossTg=0.02

L5 (GND) Copper 0.0152mm

Dielectric 5 Prepreg  
1/1 FR4 natural 0.0994mm  
3313 RC57% 4.2mil, Er=4.1, LossTg=0.02

L6 (Sig,PWR) Copper 0.035mm  
B.Mask Bottom mask (Green, 0.02mm, Solder Resist, Er=3.8)  
B.Paste Bottom paste  
B.Silkscreen Bottom silkscreen (White, Direct Printing)

Finish ENIG  
Option Impedance Controlled

PCB AREA

